



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20190424000.1
Qualify new Mount Compound Material for Select Package Device
Change Notification / Sample Request

Date: April 24, 2019
To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact the TI Samples Team at pcn_sr_team@list.ti.com.

Sincerely,

PCN Team
SC Business Services

20190424000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74HC595BRWNR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20190424000.1		PCN Date:	Apr 24, 2019							
Title:	Qualify new Mount Compound Material for Select Package Device										
Customer Contact:	PCN Manager	Dept:	Quality Services								
Proposed 1st Ship Date:	Jul. 24, 2019	Estimated Sample Availability:	Date provided at sample request								
Change Type:											
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site						
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material						
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process						
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site						
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials						
				<input type="checkbox"/>	Wafer Fab Process						
PCN Details											
Description of Change:											
Texas Instruments is pleased to announce the qualification of new mount compound material for select package device. Devices will remain in current assembly facility and piece part changes as follows:											
<table border="1"> <thead> <tr> <th>Material</th> <th>From</th> <th>To</th> </tr> </thead> <tbody> <tr> <td>Mount compound</td> <td>1400348111</td> <td>1400329111</td> </tr> </tbody> </table>						Material	From	To	Mount compound	1400348111	1400329111
Material	From	To									
Mount compound	1400348111	1400329111									
Reason for Change:											
Continuity of supply.											
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):											
None											
Anticipated impact on Material Declaration											
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.								
Changes to product identification resulting from this PCN:											
None											
Product Affected:											
SN74HC595BRWNR		SN74LVC244ARWPR									

Qualification Report

Approve Date 26-Mar-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: <u>SN74LVC244ARWPR</u>
TC	**T/C -65C/150C	-65C/+150C (500 Cycles)	1/77/0
MSL	Moisture Sensitivity (Cu Wire)	(per the appropriate pkg level)	1/12/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass
VM	Visual Quality Reliability Inspection	Post Temp Cycle	Pass
YLD	FTY and Bin Summary	-	Pass

- QBS: Qual By Similarity

- Qual Device SN74LVC244ARWPR is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

THIS INFORMATION RELATING TO QUALITY AND RELIABILITY IS PROVIDED "AS IS." Product information detailed in this report may not accurately reflect TI's current product materials, processes and testing used in the construction of the TI products. Customers are solely responsible to conduct sufficient engineering and additional qualification testing to determine whether a device is suitable for use in their applications. Using TI products outside limits stated in TI's datasheet may void TI's warranty. See TI's Terms of Sale at "<http://www.ti.com/lsds/ti/legal/termsofsale.page>"

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com